CMOS IC FROM 32K byte, RAM 1024 byte on-chip

8-bit 1-chip Microcontroller



http://onsemi.com

Overview

The LC87F2J32A is an 8-bit microcomputer that, integrates on a single chip a number of hardware features such as 32K-byte flash ROM, 1024-byte RAM, an On-chip-debugger, a 16-bit timer/counter, four 8-bit timers, a base timer serving as a time-of-day clock, a high-speed clock counter, a synchronous SIO interface, an asynchronous/synchronous SIO interface, a UART interface, two 12-bit PWM channels, a 12/8-bit 14-channel AD converter, a system clock frequency divider, remote control receive, an internal reset and an interrupt feature.

Features

- ■Flash ROM
 - 32768×8 bits
 - Capable of on-board-programming with wide range (2.2 to 5.5V) of voltage source.
 - Block-erasable in 128-byte units
 - Writable in 2-byte units

■RAM

• 1024×9 bits

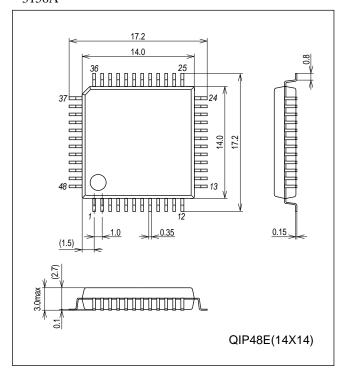
■Package Form

• QIP48E (14×14): Lead-free type

• SQFP48 (7×7): Lead-/Halogen-free type

Package Dimensions

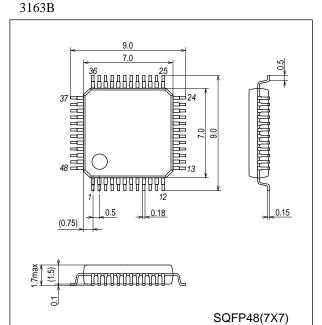
unit : mm (typ) 3156A



* This product is licensed from Silicon Storage Technology, Inc. (USA).

Package Dimensions

unit: mm (typ)



■Minimum Bus Cycle

83.3ns (12MHz) V_{DD}=2.7 to 5.5V
 100ns (10MHz) V_{DD}=2.2 to 5.5V
 250ns (4MHz) V_{DD}=1.8 to 5.5V

Note: The bus cycle time here refers to the ROM read speed.

■Minimum Instruction Cycle Time

250ns (12MHz)
 300ns (10MHz)
 750ns (4MHz)
 VDD=2.7 to 5.5V
 VDD=2.2 to 5.5V
 VDD=1.8 to 5.5V

■Ports

Normal withstand voltage I/O ports
 Ports I/O direction can be designated in 1-bit units

Dedicated oscillator ports/input portsReset pin

• Power pins

39 (P0n, P1n, P2n, P30 to P36, P70 to P73, PWM0, PWM1, XT2, CF2)

PWM1, XT2, CF2 2 (CF1, XT1)

1 (RES)

6 (VSS1 to 3, VDD1 to 3)

■Timers

• Timer 0: 16-bit timer/counter with a capture register.

Mode 0: 8-bit timer with an 8-bit programmable prescaler (with an 8-bit capture register) \times 2 channels

Mode 1: 8-bit timer with an 8-bit programmable prescaler (with an 8-bit capture register)

+ 8-bit counter (with an 8-bit capture register)

Mode 2: 16-bit timer with an 8-bit programmable prescaler (with a 16-bit capture register)

Mode 3: 16-bit counter (with a 16-bit capture register)

• Timer 1: 16-bit timer/counter that supports PWM/toggle outputs

Mode 0: 8-bit timer with an 8-bit prescaler (with toggle outputs)

+ 8-bit timer/counter with an 8-bit prescaler (with toggle outputs)

Mode 1: 8-bit PWM with an 8-bit prescaler × 2 channels

Mode 2: 16-bit timer/counter with an 8-bit prescaler (with toggle outputs) (toggle outputs also possible from the lower-order 8 bits)

Mode 3: 16-bit timer with an 8-bit prescaler (with toggle outputs)

(The lower-order 8 bits can be used as PWM.)

- Timer 4: 8-bit timer with a 6-bit prescaler
- Timer 5: 8-bit timer with a 6-bit prescaler
- Timer 6: 8-bit timer with a 6-bit prescaler (with toggle output)
- Timer 7: 8-bit timer with a 6-bit prescaler (with toggle output)
- Base timer
 - 1) The clock is selectable from the subclock (32.768kHz crystal oscillation), system clock, and timer 0 prescaler output.
- 2) Interrupts are programmable in 5 different time schemes

■High-speed Clock Counter

- 1) Can count clocks with a maximum clock rate of 20MHz (at a main clock of 10MHz)
- 2) Can generate output real-time

■SIO

- SIO0: 8-bit synchronous serial interface
 - 1) LSB first/MSB first mode selectable
 - 2) Built-in 8-bit baudrate generator (maximum transfer clock cycle=4/3 tCYC)
 - 3) Automatic continuous data transmission (1 to 256 bits, specifiable in 1-bit units, suspension and resumption of data transmission possible in 1-byte units)
- SIO1: 8-bit asynchronous/synchronous serial interface
 - Mode 0: Synchronous 8-bit serial I/O (2- or 3-wire configuration, 2 to 512 tCYC transfer clocks)
 - Mode 1: Asynchronous serial I/O (half-duplex, 8-data bits, 1-stop bit, 8 to 2048 tCYC baudrates)
 - Mode 2: Bus mode 1 (start bit, 8-data bits, 2 to 512 tCYC transfer clocks)
 - Mode 3: Bus mode 2 (start detect, 8-data bits, stop detect)

■UART

- Full duplex
- 7/8/9 bit data bits selectable
- 1 stop bit (2-bit in continuous data transmission)
- Built-in baudrate generator
- ■AD Converter: 12 bits/8 bits × 14 channels
 - 12/8 bits AD converter resolution selectable
- ■PWM: Multifrequency 12-bit PWM × 2 channels
- ■Remote Control Receiver Circuit (sharing pins with P73, INT3, and T0IN)
 - 1) Noise rejection function
 - (Units of noise rejection filter : about 120µs, when selecting a 32.768kHz crystal oscillator as a clock.)
 - 2) Supporting reception formats with a guide-pulse of halt-clock/clock/none.
 - 3) Determines a end of reception by detecting a no-signal periods (No carrier).
 - (Supports same reception format with a different bit length.)
 - 4) X'tal HOLD mode release function

■Clock Output Function

- Can generate clock outputs with a frequency of 1/1, 1/2, 1/4, 1/8, 1/16, 1/32, 1/64 of the source clock selected as the system clock.
- Can generate the source clock for the subclock.
- ■Watchdog timer
 - External RC watchdog timer
 - Interrupt and reset signals selectable

■Interrupts

- 24 sources, 10 vector addresses
 - 1) Provides three levels (low (L), high (H), and highest (X)) of multiplex interrupt control. Any interrupt requests of the level equal to or lower than the current interrupt are not accepted.
 - 2) When interrupt requests to two or more vector addresses occur at the same time, the interrupt of the highest level takes precedence over the other interrupts. For interrupts of the same level, the interrupt into the smallest vector address takes precedence.

No.	Vector Address	Level	Interrupt Source
1	00003H	X or L	INT0
2	0000BH	X or L	INT1
3	00013H	H or L	INT2/T0L/INT4/REMOREC2
4	0001BH	H or L	INT3/INT5/ BT0/BT1
5	00023H	H or L	тон
6	0002BH	H or L	T1L/T1H
7	00033H	H or L	SIO0/UART1 receive
8	0003BH	H or L	SIO1/UART1 transmit
9	00043H	H or L	ADC/T6/T7
10	0004BH	H or L	Port 0/T4/T5/PWM0, PWM1

- Priority levels X > H > L
- Of interrupts of the same level, the one with the smallest vector address takes precedence.
- IFLG (List of interrupt source flag function)
 - 1) Shows a list of interrupt source flags that caused a branching to a particular vector address (shown in the table above).
- ■Subroutine Stack Levels: 512 levels (the stack is allocated in RAM)
- ■High-speed Multiplication/Division Instructions

16 bits × 8 bits
24 bits × 16 bits
16 bits ÷ 8 bits
24 bits ÷ 16 bits
16 bits ÷ 8 bits
16 bits ÷ 16 bits
17 tCYC execution time
18 tCYC execution time
19 tcYC execution time
10 tcYC execution time
10 tcYC execution time
10 tcYC execution time
10 tcYC execution time
11 tcYC execution time
12 tcYC execution time
13 tcYC execution time
14 tcYC execution time
15 tcYC execution time
16 tcYC execution time
17 tcYC execution time
18 tcYC execution time
19 tcYC execution time
10 tcYC execution time

■Oscillation Circuits

• Internal oscillation circuits

1) Low-speed RC oscillation circuit : For system clock(100kHz)
2) Medium-speed RC oscillation circuit : For system clock(1MHz)
3) Frequency variable RC oscillation circuit: For system clock(8MHz)

(1) Adjustable in 0.5% (typ) step from a selected center frequency.

(2) Measures oscillation clock using a input signal from XT1 as a reference.

• External oscillation circuits

1) Low speed crystal oscillation circuit: For low-speed system clock, with internal Rf

2) Hi-speed CF oscillation circuit: For system clock, with internal Rf

(1) Both the CF and crystal oscillator circuits stop operation on a system reset.

■System Clock Divider Function

- Can run on low current.
- The minimum instruction cycle selectable from 300ns, 600ns, 1.2μs, 2.4μs, 4.8μs, 9.6μs, 19.2μs, 38.4μs, and 76.8μs (at a main clock rate of 10MHz).

■Internal Reset Function

- Power-on reset (POR) function
 - 1) POR reset is generated only at power-on time.
 - 2) The POR release level can be selected from 8 levels (1.67V, 1.97V, 2.07V, 2.37V, 2.57V, 2.87V, 3.86V, and 4.35V) through option configuration.
- Low-voltage detection reset (LVD) function
 - 1) LVD and POR functions are combined to generate resets when power is turned on and when power voltage falls below a certain level.
 - 2) The use/disuse of the LVD function and the low voltage threshold level (7 levels: 1.91V, 2.01V, 2.31V, 2.51V, 2.81V, 3.79V, 4.28V).

■Standby Function

- HALT mode: Halts instruction execution while allowing the peripheral circuits to continue operation.
 - 1) Oscillation is not halted automatically.
 - 2) There are three ways of resetting the HALT mode.
 - (1) Setting the reset pin to the low level
 - (2) System resetting by watchdog timer or low-voltage detection
 - (3) Occurrence of an interrupt
- HOLD mode: Suspends instruction execution and the operation of the peripheral circuits.
 - 1) The CF, RC, and crystal oscillators automatically stop operation.
 - 2) There are four ways of resetting the HOLD mode.
 - (1) Setting the reset pin to the low level.
 - (2) System resetting by watchdog timer or low-voltage detection
 - (3) Having an interrupt source established at either INT0, INT1, INT2, INT4, or INT5
 - * INTO and INT1 HOLD mode reset is available only when level detection is set.
 - (4) Having an interrupt source established at port 0
- X'tal HOLD mode: Suspends instruction execution and the operation of the peripheral circuits except the base timer.
 - 1) The CF and RC oscillators automatically stop operation.
 - 2) The state of crystal oscillation established when the X'tal HOLD mode is entered is retained.
 - 3) There are six ways of resetting the X'tal HOLD mode.
 - (1) Setting the reset pin to the low level
 - (2) System resetting by watchdog timer or low-voltage detection
 - (3) Having an interrupt source established at either INT0, INT1, INT2, INT4, or INT5
 - * INT0 and INT1 HOLD mode reset is available only when level detection is set.
 - (4) Having an interrupt source established at port 0
 - (5) Having an interrupt source established in the base timer circuit
 - (6) Having an interrupt source established in the infrared remote controller receiver circuit

■On-chip Debugger

- Supports software debugging with the IC mounted on the target board (LC87D2J32A). LC87F2J32A has an On-chip debugger but its function is limited.
- ■Data Security Function (flash versions only)
 - Protects the program data stored in flash memory from unauthorized read or copy.

 Note: This data security function does not necessarily provide absolute data security.

■Development Tools

• On-chip debugger: TCB87- TypeB + LC87D2J32A

■Programming Board

Package	Programming boards
SQFP48 (7×7)	W87F55256SQ
QIP48E (14×14)	W87F55256Q

■Flash ROM Programmer

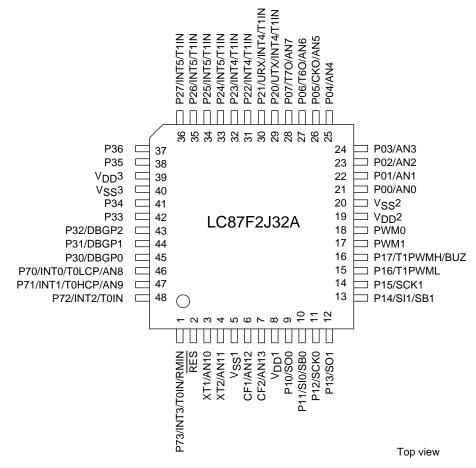
Ма	ker	Model	Supported version	Device	
Flash Support Group, Inc. (FSG)	Single programmer	AF9708 AF9709/AF9709B/AF9709C (Including Ando Electric Co., Ltd. models)	Rev 03.07 or later	LC87F2J32A	
	Cong programmer	AF9723/AF9723B(Main body) (Including Ando Electric Co., Ltd. models)	-		
	Gang programmer	AF9833(Unit) (Including Ando Electric Co., Ltd. models)	-	-	
Flash Support Group, Inc. (FSG)	In-circuit programmer	AF9101/AF9103(Main body) (FSG models)	(Note 2)	LC87F2J32A	
Our company (Note 1)	in cheat programmer	SIB87(Inter Face Driver) (Our company model)	(11010 2)	LC071 2332A	
Our company	Single/Gang programmer	SKK/SKK Type B (SANYO FWS)	Application Version 1.04 or later	LC87F2J32A	
Ca. company	In-circuit/ Gang programmer	SKK-DBG Type B (SANYO FWS)	Chip Data Version 2.16 or later		

 $Note 1: On-board-programmer \ from \ FSG \ (AF9101/AF9103) \ and \ serial \ interface \ driver \ from \ Our \ company \ (SIB87) \ together$

can give a PC-less, standalone on-board-programming capabilities.

Note2: It needs a special programming devices and applications depending on the use of programming environment. Please ask FSG or Our company for the information.

Pin Assignment



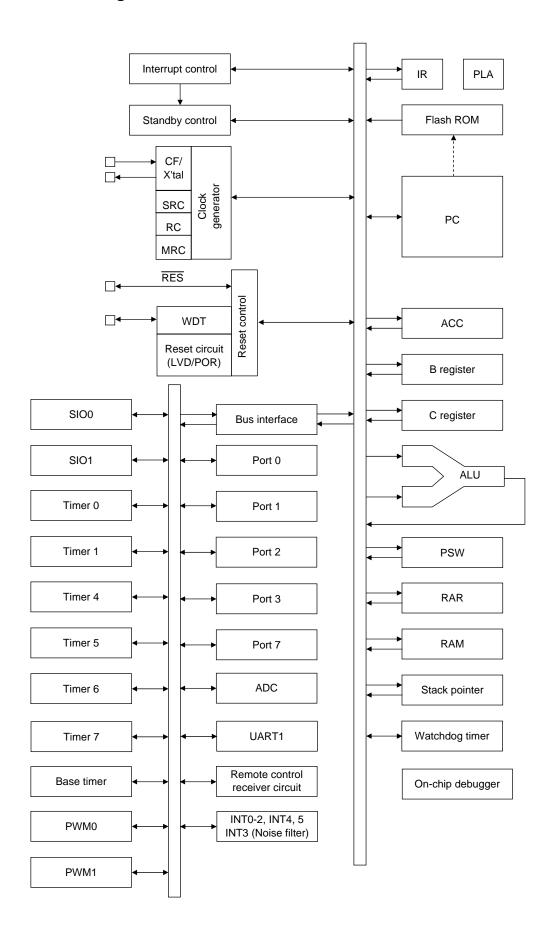
SQFP48 (7×7) "Lead- / Halogen-free Type" QIP48E (14×14) "Lead-free Type"

SQFP/QIP	NAME
1	P73/INT3/T0IN/RMIN
2	RES
3	XT1/AN10
4	XT2/AN11
5	V _{SS} 1
6	CF1/AN12
7	CF2/AN13
8	V _{DD} 1
9	P10/SO0
10	P11/SI0/SB0
11	P12/SCK0
12	P13/SO1
13	P14/SI1/SB1
14	P15/SCK1
15	P16/T1PWML
16	P17/T1PWMH/BUZ

SQFP/QIP	NAME
17	PWM1
18	PWM0
19	V _{DD} 2
20	V _{SS} 2
21	P00/AN0
22	P01/AN1
23	P02/AN2
24	P03/AN3
25	P04/AN4
26	P05/CKO/AN5
27	P06/T6O/AN6
28	P07/T7O/AN7
29	P20/UTX/INT4/T1IN
30	P21/URX/INT4/T1IN
31	P22/INT4/T1IN
32	P23/INT4/T1IN

SQFP/QIP	NAME
33	P24/INT5/T1IN
34	P25/INT5/T1IN
35	P26/INT5/T1IN
36	P27/INT5/T1IN
37	P36
38	P35
39	V _{DD} 3
40	V _{SS} 3
41	P34
42	P33
43	P32/DBGP2
44	P31/DBGP1
45	P30/DBGP0
46	P70/INT0/T0LCP/AN8
47	P71/INT1/T0HCP/AN9
48	P72/INT2/T0IN

System Block Diagram



Pin Description

Pin Name	I/O			D	escription			Option	
V _{SS} 1 to V _{SS} 3	-	- power supp	power supply pins					No	
V _{DD} 1 to V _{DD} 3	-	+ power sup	power supply pin						
Port 0	I/O	• 8-bit I/O po	t I/O port						
P00 to P07		•	ble in 1-bit units						
1 00 10 1 07			istors can be turn	ed on and off in	1-bit units.				
		HOLD rese	et input						
		Port 0 inter	rupt input						
		Pin function	ns						
		P05: Syste	m clock output						
		P06: Timer	6 toggle output						
		P07: Timer	7 toggle output						
		P00(AN0) t	to P07(AN7): AD	converter input					
Port 1	I/O	• 8-bit I/O po							
P10 to P17		 I/O specifia 	ble in 1-bit units						
		Pull-up resi	istors can be turn	ed on and off in	1-bit units.				
		Pin function	ns						
		P10: SIO0	data output						
		P11: SIO0	data input/bus I/0)					
		P12: SIO0	clock I/O						
		P13: SIO1 data output							
			data input / bus I	/O					
		P15: SIO1							
			1PWML output						
	1		1PWMH output/	beeper output					
Port 2	I/O	• 8-bit I/O po						Yes	
P20 to P27			ble in 1-bit units						
			Pull-up resistors can be turned on and off in 1-bit units.						
		• Pin functions							
		P20: UART							
			P21: UART receive P20 to P23: INT4 input/HOLD reset input/timer 1 event input/timer 0L capture input/ timer 0H capture input P24 to P27: INT5 input/HOLD reset input/timer 1 event input/timer 0L capture input/						
		P20 to P23							
		D24 to D27							
		P24 to P27		· ·	er i event input/tir	ner oL capture ir	nput/		
		Interrupt of	timer 0H captur	e input					
		interrupt ac	knowledge type		Dining 9				
			Rising	Falling	Rising &	H level	L level		
		INT4	enable	enable	Falling enable	disable	disable		
		INT5	enable	enable	enable	disable	disable		
		IIVIO	CHADIC	enable	CHADIC	uisabie	uisabie		
Port 3	I/O	• 7-bit I/O po	rt					Yes	
P30 to P36	1		ble in 1-bit units						
		Pull-up resi	istors can be turn	ed on and off in	1-bit units.				
		Shared pin							
		On-chip de	bugger pins: DB0	GP0 to DBGP2 (F	P30 to P32)				

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Pin Name	I/O			D	escription			Option
Port 7	I/O	• 4-bit I/O po	ort					No
P70 to P73		• I/O specifiable in 1-bit units						
		Pull-up resistors can be turned on and off in 1-bit units.						
		Pin function	ns					
		P70: INT0	input/HOLD reset	input/timer 0L ca	apture input/watch	dog timer output		
		P71: INT1	input/HOLD reset	input/timer 0H ca	apture input			
		P72: INT2	input HOLD reset	input/timer 0 eve	ent input/timer 0L	capture input		
		P73: INT3	input (with noise f	ilter)/timer 0 ever	nt input/timer 0H o	apture input		
		P70(AN8),	P71(AN9) : AD co	onverter input				
		Interrupt ac	cknowledge type					
			Distrac	Fallia a	Rising &	1115	Libraria	
			Rising	Falling	Falling	H level	L level	
		INT0	enable	enable	disable	enable	enable	
		INT1	enable	enable	disable	enable	enable	
		INT2	enable	enable	enable	disable	disable	
		INT3	enable	enable	enable	disable	disable	
PWM0, PWM1	I/O	PWM0 and PWM1 output ports						
		• General-pu	ırpose I/O availab	le				
RES	I/O	External res	et Input/internal re	eset output				No
XT1	Input	32.768kHz crystal oscillator input pin						No
		Shared pins						
		General-pu	irpose input port					
		AD convert	ter input port: AN1	10				
XT2	I/O • 32.768kHz crystal oscillator output pin							No
		 Shared pin 	S					
		General-pu	rpose I/O port					
		AD convert	ter input port: AN1	11				
CF1	Input	Ceramic res	onator input pin					No
		Shared pin	S					
		General-pu	rpose input port					
		AD convert	ter input port: AN1	12				
CF2	Output	Ceramic res	onator output pin				<u> </u>	No
		Shared pin						
		General-pu	rpose I/O port					
		AD convert	ter input port: AN1	13				

On-chip Debugger Pin Connection Requirements

For the treatment of the on-chip debugger pins, refer to the separately available documents entitled "RD87 On-chip Debugger Installation Manual"

Recommended Unused Pin Connections

Dord Mosso	Recommended Unused Pin Connections				
Port Name	Board	Software			
P00 to P07	Open	Output low			
P10 to P17	Open	Output low			
P20 to P21	Open	Output low			
P30 to P36	Open	Output low			
P70 to P73	Open	Output low			
PWM0,PWM1	Open	Output low			
XT1	Pulled low with a 100kΩ resistor or less	General-purpose input port			
XT2	Open	Output low			
CF1	Pulled low with a 100kΩ resistor or less	General-purpose input port			
CF2	Open	Output low			

Port Output Types

The table below lists the types of port outputs and the presence/absence of a pull-up resistor. Data can be read into any input port even if it is in the output mode.

Port Name	Option Selected in Units of	Option Type	Output Type	Pull-up Resistor
P00 to P07	1 bit	1	CMOS	Programmable (Note 1)
		2	Nch-open drain	Programmable (Note 1)
P10 to P17	1 bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
P20 to P27	1 bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
P30 to P36	1 bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
P70	-	No	Nch-open drain	Programmable
P71 to P73	-	No	CMOS	Programmable
PWM0, PWM1	-	No	CMOS	No
XT1	-	No	Input for 32.768kHz crystal oscillator (Input only)	No
XT2	-	No	Output for 32.768kHz crystal oscillator (Nch-open drain when in general-purpose output mode)	No
CF1	-	No	Input for ceramic resonator oscillator (Input only)	No
CF2	-	No	Output for ceramic resonator oscillator (Nch-open drain when in general-purpose output mode)	No

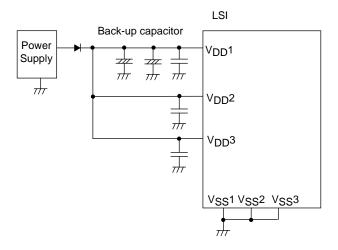
Note 1: The control of the presence or absence of the programmable pull-up resistors for port 0 and the switching between low- and high-impedance pull-up connection is exercised in 1-bit units.

User Option Table

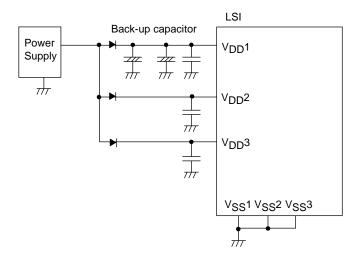
Option name	Option to be applied on	Flash-ROM version	Option selected in units of	Option selection
Port output type	B00 (B07		4.12	CMOS
	P00 to P07	0	CMOS	Nch-open drain
	B. 0 B. =	_	415	CMOS
	P10 to P17	0	1 DIT	Nch-open drain
	D00 / D07		412	CMOS
	P20 to P27	O	1 DIT	Nch-open drain
	B00 / B00	0	1 bit	CMOS
	P30 to P36			Nch-open drain
Program start		0		00000h
address	-	O	-	07E00h
Low-voltage	B			Enable: Use
detection reset	am start ss - O oltage ion reset on Detect level O	O	-	Disable: Not Used
function	Detect level	0	-	7-level
Power-on reset function	Power-On reset level	0	-	8-level

Note: To reduce V_{DD} signal noise and to increase the duration of the backup battery supply, V_{SS}1, V_{SS}2, and V_{SS}3 should connect to each other and they should also be grounded.

Example 1: During backup in hold mode, port output 'H' level is supplied from the back-up capacitor.



Example 2: During backup in hold mode, output is not held high and its value in unsettled.



Absolute Maximum Ratings at $Ta=25^{\circ}C,\ V_{SS}1=V_{SS}2=V_{SS}3=0V$

		1			, 225	Ι .			
	Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	Spec	ification max	unit
	iximum supply	V _{DD} max	V _{DD} 1, V _{DD} 2, V _{DD} 3	V _{DD} 1=V _{DD} 2=V _{DD} 3	- 001-1	-0.3	-91	+6.5	
	out voltage	VI	XT1, CF1			-0.3		V _{DD} +0.3	
	out/output tage	V _{IO}	Ports 0, 1, 2, 3, Port 7, PWM0, PWM1, XT2, CF2			-0.3		V _{DD} +0.3	V
	Peak output current	IOPH(1)	Ports 0, 1, 2, 3	CMOS output select Per 1 applicable pin		-10			
	Carrent	IOPH(2)	PWM0, PWM1	т ст таррисавіс ріт		-20			
		IOPH(3)	P71 to P73	Per 1 applicable pin		-5			
High level output current	Mean output	IOMH(1)	Ports 0, 1, 2, 3	CMOS output select Per 1 applicable pin		-7.5			
	(Note 1-1)	IOMH(2)	PWM0, PWM1	r or r approadic pin		-15			
ntbut		IOMH(3)	P71 to P73	Per 1 applicable pin		-3			
el o	Total output	ΣΙΟΑΗ(1)	P71 to P73	Total of all applicable pins		-10			
lev ר	current	ΣΙΟΑΗ(2)	Port 0	Total of all applicable pins		-25			
Hig		ΣΙΟΑΗ(3)	Port 1, PWM0, PWM1	Total of all applicable pins		-25			
		ΣΙΟΑΗ(4)	Ports 0, 1,PWM0, PWM1	Total of all applicable pins		-45			
		ΣΙΟΑΗ(5)	Ports 2, P35, P36	Total of all applicable pins		-25			mA
		ΣΙΟΑΗ(6)	P30 to P34	Total of all applicable pins		-25			
		ΣΙΟΑΗ(7)	Pots 2, 3	Total of all applicable pins		-45			
	Peak output current Mean output current (Note 1-1)	IOPL(1)	P02 to P07, Ports 1, 2, 3, PWM0, PWM1	Per 1 applicable pin				20	
		IOPL(2)	P00, P01	Per 1 applicable pin				30	
		IOPL(3)	Port 7, XT2, CF2	Per 1 applicable pin				10	
Low level output current		IOML(1)	P02 to P07, Ports 1, 2, 3, PWM0, PWM1	Per 1 applicable pin				15	
but ((14010-1-1)	IOML(2)	P00, P01	Per 1 applicable pin				20	Ì
l out		IOML(3)	Port 7, XT2, CF2	Per 1 applicable pin				7.5	
leve	Total output	ΣIOAL(1)	Port 7, XT2, CF2	Total of all applicable pins				15	
_ow	current	ΣIOAL(2)	Port 0	Total of all applicable pins				45	
		ΣIOAL(3)	Port 1, PWM0, PWM1	Total of all applicable pins				45	
		ΣIOAL(4)	Port 0, 1, PWM0, PWM1	Total of all applicable pins				80	
		ΣIOAL(5)	Ports 2, P35, P36	Total of all applicable pins				45	
		ΣIOAL(6)	P30 to P34	Total of all applicable pins				45	
		ΣIOAL(7)	Ports 2, 3	Total of all applicable pins				60	
Po	wer dissipation	Pd max(1)	SQFP48 (7×7)	Ta=-40 to +85°C Package only				139	
		Pd max(2)		Ta=-40 to +85°C Package with thermal resistance board (Note 1-2)				356	
		Pd max(3)	QIP48E (14×14)	Ta=-40 to +85°C Package only				281	mV
		Pd max(4)		Ta=-40 to +85°C Package with thermal resistance board (Note 1-2)				489	
	erating ambient	Topr				-40		+85	
Sto	orage ambient	Tstg				-55		+125	°C

Note 1-1: The mean output current is a mean value measured over 100ms.

Note 1-2: SEMI standards thermal resistance board (size: 76.1×114.3×1.6tmm, glass epoxy) is used.

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Allowable Operating Conditions at Ta = -40 °C to +85 °C, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

	1			DD	DD	Specifi	cation	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Operating	V _{DD} (1)	V _{DD} 1=V _{DD} 2=V _{DD} 3	0.245μs≤tCYC≤200μs	55	2.7		5.5	
supply voltage	V _{DD} (2)		0.294μs≤tCYC≤200μs		2.2		5.5	
(Note 2-1)	V _{DD} (3)		0.735μs≤tCYC≤200μs		1.8		5.5	
Memory sustaining supply voltage	VHD	V _{DD} 1=V _{DD} 2=V _{DD} 3	RAM and register contents sustained in HOLD mode.		1.6		5.5	
High level input voltage	V _{IH} (1)	Ports 1, 2, 3, P71 to P73 P70 port input/ interrupt side PWM0, PWM1		1.8 to 5.5	0.3V _{DD} +0.7		V _{DD}	
	V _{IH} (2)	Port 0		1.8 to 5.5	0.3V _{DD} +0.7		V _{DD}	
	V _{IH} (3)	Port 70 watchdog timer side		1.8 to 5.5	0.9V _{DD}		V _{DD}	V
	V _{IH} (4)	XT1, XT2, CF1, CF2, RES		1.8 to 5.5	0.75V _{DD}		V _{DD}	
Low level input voltage	V _{IL} (1)	Ports 1, 2, 3, P71 to P73		4.0 to 5.5	V _{SS}		0.1V _{DD} +0.4	
		P70 port input/ interrupt side PWM0, PWM1		1.8 to 4.0	V _{SS}		0.2V _{DD}	
	V _{IL} (2)	Port 0		4.0 to 5.5	Vss		0.15V _{DD} +0.4	
				1.8 to 4.0	V _{SS}		0.2V _{DD}	
	V _{IL} (3)	Port 70 watchdog timer side		1.8 to 5.5	V _{SS}		0.8V _{DD} -1.0	
	V _{IL} (4)	XT1, XT2, CF1, CF2, RES		1.8 to 5.5	V _{SS}		0.25V _{DD}	
Instruction	tCYC			2.7 to 5.5	0.245		200	
cycle time	(Note 2-2)			2.2 to 5.5	0.294		200	μs
(Note 2-1)				1.8 to 5.5	0.735		200	
External	FEXCF	CF1	CF2 pin open	2.7 to 5.5	0.1		12	
system clock frequency			System clock frequency division ratio=1/1 External system clock duty= 50±5%	1.8 to 5.5	0.1		4	
			CF2 pin open	3.0 to 5.5	0.2		24.4	MHz
			System clock frequency division ratio=1/2 External system clock duty= 50±5%	2.0 to 5.5	0.2		8	
Oscillation frequency	FmCF(1)	CF1, CF2	12MHz ceramic oscillation See Fig. 1.	2.7 to 5.5		12		
range (Note 2-3)	FmCF(2)	CF1, CF2	10MHz ceramic oscillation See Fig. 1.	2.2 to 5.5		10		
	FmCF(3)	CF1, CF2	4MHz ceramic oscillation. CF oscillation normal amplifier size selected. See Fig. 1. CFLAMP=0)	1.8 to 5.5		4		MHz
			4MHz ceramic oscillation. CF oscillation low amplifier size selected. (CFLAMP=1) See Fig. 1.	2.2 to 5.5		4		

Note 2-1: V_{DD} must be held greater than or equal to 2.2V in the flash ROM onboard programming mode.

Note 2-2: Relationship between tCYC and oscillation frequency is 3/FmCF at a division ratio of 1/1 and 6/FmCF at a division ratio of 1/2.

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Continued from preceding page.

D	0	D: /D	0 1111			Specifi	cation	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Oscillation frequency range	FmMRC(1)		Frequency variable RC oscillation. 1/2 frequency division ratio. (RCCTD=0) (Note 2-4)	2.4 to 5.5	7.44	8.0	8.56	
(Note 2-3)	FmMRC(2)		Frequency variable RC oscillation. 1/2 frequency division ratio. (RCCTD=0) Ta=-10 to +50°C (Note 2-4)	2.4 to 5.5	7.6	8.0	8.4	MHz
	FmRC		Internal Medium-speed RC oscillation	1.8 to 5.5	0.5	1.0	2.0	
	FmSRC		Internal Low-speed RC oscillation	1.8 to 5.5	50	100	200	
	FsX'tal	XT1, XT2	32.768kHz crystal oscillation See Fig. 3.	1.8 to 5.5		32.768		kHz
Frequency variable RC oscillation usable range	OpVMRC		Frequency variable RC oscillation. 1/2 frequency division ratio. (RCCTD=0)	2.4 to 5.5	6	8	10	MHz
Frequency variable RC	VmADJ(1)		Each step of VMRCHBn	2.4 to 5.5	3.6	7.0	11	
oscillation	VmADJ(2)		Each step of VMFCHBn	2.4 to 5.5	0.7	1.5	2.3	%
adjustment range	VmADJ(3)		Each step of VMDCHn	2.4 to 5.5	0.2	0.5	1.1	

Note 2-3: See Tables 1 and 2 for the oscillation constants.

Note 2-4: When switching the system clock, allow an oscillation stabilization time of $100\mu s$ or longer after the multifrequency RC oscillator circuit transmits from the "oscillation stopped" to "oscillation enabled" state.

Electrical Characteristics at Ta = -40°C to +85°C, V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V

Doromotor	neter Symbol Pin/Remarks Conditions				Specific	ation		
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
High level input current	I _{IH} (1)	Ports 0, 1, 2, 3 Ports 7 RES PWM0, PWM1	Output disabled Pull-up resistor off VIN=VDD (Including output Tr's off leakage current)	1.8 to 5.5			1	
	I _{IH} (2)	XT1, XT2, CF2	Input port selected VIN=VDD	1.8 to 5.5			1	
	I _{IH} (3)	CF1	V _{IN} =V _{DD}	1.8 to 5.5			15	
Low level input current	I _{IL} (1)	Ports 0, 1, 2, 3 Port 7 RES PWM0, PWM1	Output disabled Pull-up resistor off VIN=VSS (Including output Tr's off leakage current)	1.8 to 5.5	-1			μΑ
	I _I L(2)	XT1, XT2, CF2	Input port selected V _{IN} =V _{SS}	1.8 to 5.5	-1			
	I _{IL} (3)	CF1	V _{IN} =V _{SS}	1.8 to 5.5	-15			
High level	V _{OH} (1)	Ports 0, 1, 2, 3,	I _{OH} =-1mA	4.5 to 5.5	V _{DD} -1			
output voltage	V _{OH} (2)	P71 to P73	I _{OH} =-0.35mA	2.7 to 5.5	V _{DD} -0.4			
-	V _{OH} (3)		I _{OH} =-0.15mA	1.8 to 5.5	V _{DD} -0.4			
	V _{OH} (4)	PWM0, PWM1,	I _{OH} =-6mA	4.5 to 5.5	V _{DD} -1			
	V _{OH} (5)	P05(System clock output function	I _{OH} =-1.4mA	2.7 to 5.5	V _{DD} -0.4			
	V _{OH} (6)	used)	I _{OH} =-0.8mA	1.8 to 5.5	V _{DD} -0.4			V
Low level	V _{OL} (1)	Ports 0, 1, 2, 3,	I _{OL} =10mA	4.5 to 5.5			1.5	
output voltage	V _{OL} (2)	PWM0, PWM1,	I _{OL} =1.4mA	2.7 to 5.5			0.4	
	V _{OL} (3)		I _{OL} =0.8mA	1.8 to 5.5			0.4	
	V _{OL} (4)	P00, P01	I _{OL} =25mA	4.5 to 5.5			1.5	
	V _{OL} (5)		I _{OL} =4mA	2.7 to 5.5			0.4	
	V _{OL} (6)		I _{OL} =2mA	1.8 to 5.5			0.4	
	V _{OL} (7)	Port 7, XT2, CF2	I _{OL} =1.4mA	2.7 to 5.5			0.4	
	V _{OL} (8)		I _{OL} =0.8mA	1.8 to 5.5			0.4	
Pull-up	Rpu(1)	Ports 0, 1, 2, 3	V _{OH} =0.9V _{DD}	4.5 to 5.5	15	35	80	
resistance	Rpu(2)	Port 7	When Port 0 selected low-impedance pull-up.	1.8 to 4.5	18	50	230	kΩ
	Rpu(3)	Port 0	V _{OH} =0.9V _{DD} When Port 0 selected High-impedance pull-up.	1.8 to 5.5	100	210	400	KS2
Hysteresis voltage	VHYS(1)	Ports 1, 2, 3, 7, RES, XT2		2.7 to 5.5		0.1 V _{DD}		V
	VHYS(2)			1.8 to 2.7		0.07 V _{DD}		V
Pin capacitance	СР	All pins	For pins other than that under test: VIN=VSS, f=1MHz, Ta=25°C	1.8 to 5.5		10		pF

Serial Input/Output Characteristics at $Ta=-40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1=V_{SS}2=V_{SS}3=0V$ 1. SIO0 Serial I/O Characteristics (Note 4-1-1)

) aramatar	Cumbal	Pin/Remarks	Conditions			Speci	fication	
	-	Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
		Frequency	tSCK(1)	SCK0(P12)	• See Fig. 6.		2			
	Input clock	Low level pulse width	tSCKL(1)			1.8 to 5.5	1			40)(0
Serial clock	lupi	High level pulse width	tSCKH(1)				1			tCYC
erial	×	Frequency	tSCK(2)	SCK0(P12)	CMOS output selected		4/3			
S	Output clock	Low level pulse width	tSCKL(2)		• See Fig. 6	1.8 to 5.5		1/2		tSCK
	Outp	High level pulse width	tSCKH(2)					1/2		ISCK
put	Da	ta setup time	tsDI(1)	SB0(P11), SI0(P11)	Must be specified with respect to rising edge of		0.05			
Serial input	Da	ta hold time	thDI(1)		SIOCLK. • See Fig. 6.	1.8 to 5.5	0.05			
	Input clock	Output delay time	tdD0(1)	SO0(P10), SB0(P11)	Continuous data transmission/reception mode (Note 4-1-2)				(1/3)tCYC +0.08	μs
output	Inpu		tdD0(2)		Synchronous 8-bit mode (Note 4-1-2)	1.8 to 5.5			1tCYC +0.08	
Serial	Serial output Output clock Inp		tdD0(3)		(Note 4-1-2)	1.0 to 0.0			(1/3)tCYC +0.08	

Note 4-1-1: These specifications are theoretical values. Add margin depending on its use.

Note 4-1-2: Must be specified with respect to falling edge of SIOCLK. Must be specified as the time to the beginning of output state change in open drain output mode. See Fig. 6.

2. SIO1 Serial I/O Characteristics (Note 4-2-1)

)	O. made al	Dia /Damada	Constitues -			Specif	ication	
	ŀ	Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
		Frequency	tSCK(3)	SCK1(P15)	• See Fig. 6.		2			
	Input clock	Low level pulse width	tSCKL(3)			1.8 to 5.5	1			10)(0
Serial clock	lub	High level pulse width	tSCKH(3)				1			tCYC
erial	~	Frequency	tSCK(4)	SCK1(P15)	CMOS output selected		2			
ŭ	out clock	Low level pulse width	tSCKL(4)		• See Fig. 6.	1.8 to 5.5		1/2		10014
	Output	High level pulse width	tSCKH(4)				1/2			tSCK
put	Da	ta setup time	tsDI(2)	SB1(P14), SI1(P14)	Must be specified with respect to rising edge of		0.05			
Serial input	Da	ta hold time	thDI(2)		SIOCLK. • See Fig. 6.	1.8 to 5.5	0.05			
Serial output	Ou	tput delay time	tdD0(4)	SO1(P13), SB1(P14)	Must be specified with respect to falling edge of SIOCLK. Must be specified as the time to the beginning of output state change in open drain output mode. See Fig. 6.	1.8 to 5.5			(1/3)tCYC +0.08	μѕ

Note 4-2-1: These specifications are theoretical values. Add margin depending on its use.

Pulse Input Conditions at Ta = -40°C to +85°C, $V_SS1 = V_SS2 = V_SS3 = 0V$

Doromotor	Symbol	Pin/Remarks	Conditions			Specif	fication	
Parameter	Symbol	Pin/Remarks	Conditions	VDD[V]	min	typ	max	unit
High/low level	tPIH(1)	INT0(P70),	Interrupt source flag can be set.					
pulse width	tPIL(1)	INT1(P71),	Event inputs for timer 0 or 1 are					
		INT2(P72),	enabled.	1.8 to 5.5	1			
		INT4(P20 to P23)						
		INT5(P24 to P27)						
	tPIH(2)	INT3(P73) when	Interrupt source flag can be set.					
	tPIL(2)	noise filter time	Event inputs for timer 0 are enabled.	1.8 to 5.5	2			tCYC
		constant is 1/1						icic
	tPIH(3)	INT3(P73) when	Interrupt source flag can be set.					
	tPIL(3)	noise filter time	Event inputs for timer 0 are enabled.	1.8 to 5.5	64			
		constant is 1/32						
	tPIH(4)	INT3(P73) when	Interrupt source flag can be set.					
	tPIL(4)	noise filter time	Event inputs for timer 0 are enabled.	1.8 to 5.5	256			
		constant is 1/128						
	tPIL(5)	RES	Resetting is enabled.	1.8 to 5.5	200			μs

AD Converter Characteristics at $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

<12bits AD Converter Mode at Ta = -40 to +85°C>

	0	D: (D	O Pri			Specif	ication	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Resolution	N	AN0(P00) to		2.4 to 5.5		12		bit
Absolute	ET	AN7(P07)	(Note 6-1)	3.0 to 5.5			±16	1.00
accuracy		AN8(P70) - AN9(P71)	(Note 6-1)	2.4 to 3.6			±20	LSB
Conversion	TCAD	AN10(XT1)	See Conversion time calculation	4.0 to 5.5	32		115	
time		AN11(XT2)	formulas (Note 6-2)	3.0 to 5.5	64		115	μs
		AN12(CF1) AN13(CF2)	See Conversion time calculation formulas. (Note 6-2)	2.4 to 3.6	410		425	μο
Analog input voltage range	VAIN			2.4 to 5.5	V _{SS}		V_{DD}	٧
Analog port	IAINH(1)	analog channel	VAIN=V _{DD}	2.4 to 5.5			1	
input current	IAINL(1)	except AN12	VAIN=V _{SS}	2.4 to 5.5	-1			
	IAINH(2)	AN12	VAIN=V _{DD}	2.4 to 5.5			15	μΑ
	IAINL(2)		VAIN=V _{SS}	2.4 to 5.5	-15			

- Note 6-1: The quantization error $(\pm 1/2LSB)$ must be excluded from the absolute accuracy. The absolute accuracy must be measured in the microcontroller's state in which no I/O operations occur at the pins adjacent to the analog input channel.
- Note 6-2: The conversion time refers to the period from the time an instruction for starting a conversion process till the time the conversion results register(s) are loaded with a complete digital conversion value corresponding to the analog input value.

The conversion time is 2 times the normal-time conversion time when:

- The first AD conversion is performed in the 12-bit AD conversion mode after a system reset.
- The first AD conversion is performed after the AD conversion mode is switched from 8-bit to 12-bit conversion mode.

<8bits AD Converter Mode at Ta = -40 to +85°C>

D	Oh al	Pin/Remarks	Condition -			Specif	ication	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Resolution	N	AN0(P00) to		2.4 to 5.5		8		bit
Absolute accuracy	ET	AN7(P07) AN8(P70)	(Note 6-1)	2.4 to 5.5			±1.5	LSB
Conversion	TCAD	AN9(P71)	See Conversion time calculation	4.0 to 5.5	20		90	
time	AN11(XT2) AN12(CF1)	formulas. (Note 6-2)	3.0 to 5.5	40		90	μs	
		, ,	See Conversion time calculation formulas. (Note 6-2)	2.4 to 3.6	250		265	μσ
Analog input voltage range	VAIN	711110(012)		2.4 to 5.5	V _{SS}		V _{DD}	>
Analog port	IAINH(1)	analog channel	VAIN=V _{DD}	2.4 to 5.5			1	
input current IA	IAINL(1)	except AN12	VAIN=V _{SS}	2.4 to 5.5	-1			
	IAINH(2)	AN12	VAIN=V _{DD}	2.4 to 5.5			15	μΑ
	IAINL(2)	1	VAIN=V _{SS}	2.4 to 5.5	-15			

Conversion time calculation formulas:

12bits AD Converter Mode: TCAD(Conversion time)= ((52/(AD division ratio))+2)×(1/3)×tCYC 8bits AD Converter Mode: TCAD(Conversion time)=((32/(AD division ratio))+2)×(1/3)×tCYC

External oscillation	Operating supply voltage range	System division ratio	Cycle time (tCYC)	AD division ratio		
(FmCF)	(V _{DD})	(SYSDIV)	(tCYC)	(ADDIV)	12bit AD	8bit AD
OF 40M11-	4.0V to 5.5V	1/1	250ns	1/8	34.8µs	21.5μs
CF-12MHz	3.0V to 5.5V	1/1	250ns	1/16	69.5µs	42.8µs
OF 40M1-	4.0V to 5.5V	1/1	300ns	1/8	41.8µs	25.8μs
CF-10MHz	3.0V to 5.5V	1/1	300ns	1/16	83.4µs	51.4μs
05 444	3.0V to 5.5V	1/1	750ns	1/8	104.5μs	64.5µs
CF-4MHz	2.4V to 3.6V	1/1	750ns	1/32	416.5μs	256.5μs

- Note 6-1: The quantization error $(\pm 1/2LSB)$ must be excluded from the absolute accuracy. The absolute accuracy must be measured in the microcontroller's state in which no I/O operations occur at the pins adjacent to the analog input channel.
- Note 6-2: The conversion time refers to the period from the time an instruction for starting a conversion process till the time the conversion results register(s) are loaded with a complete digital conversion value corresponding to the analog input value.

The conversion time is 2 times the normal-time conversion time when:

- The first AD conversion is performed in the 12-bit AD conversion mode after a system reset.
- The first AD conversion is performed after the AD conversion mode is switched from 8-bit to 12-bit conversion mode.

Power-on reset (POR) Characteristics at Ta = -40 to +85°C, VSS1 = VSS2 = VSS3 = 0V

	Symbol	Pin/Remarks			Specification				
Parameter			Conditions	Option selected voltage	min	typ	max	unit	
POR release	PORRL		Select from option.	1.67V	1.55	1.67	1.79		
voltage			(Note 7-1)	1.97V	1.85	1.97	2.09		
				2.07V	1.95	2.07	2.19		
				2.37V	2.25	2.37	2.49		
				2.57V	2.45	2.57	2.69	V	
				2.87V	2.75	2.87	2.99	v	
				3.86V	3.73	3.86	3.99		
				4.35V	4.21	4.35	4.49		
Detection voltage unknown state	POUKS		• See Fig. 8. (Note 7-2)			0.7	0.95		
Power supply rise time	PORIS		Power supply rise time from 0V to 1.6V.				100	ms	

Note7-1: The POR release level can be selected out of 8 levels only when the LVD reset function is disabled.

Note7-2: POR is in an unknown state before transistors start operation.

					Specification			
Parameter	Symbol	Pin/Remarks	Conditions	Option selected voltage	min	typ	max	unit
LVD reset	LVDET		Select from option.	1.91V	1.81	1.91	2.01	
Voltage			(Note 8-1)	2.01V	1.91	2.01	2.11	
(Note 8-2)			(Note 8-3) • See Fig. 9.	2.31V	2.21	2.31	2.41	
			• See Fig. 9.	2.51V	2.41	2.51	2.61	V
				2.81V	2.71	2.81	2.91	
				3.79V	3.69	3.79	3.89	
				4.28V	4.18	4.28	4.38	
LVD hysteresis	LVHYS			1.91V		55		
width				2.01V		55		
				2.31V		55		
				2.51V		55		mV
				2.81V		60		
				3.79V		65		
				4.28V		65		
Detection voltage unknown state	LVUKS		• See Fig. 9. (Note 8-4)			0.7	0.95	V
Low voltage detection minimum width (Reply sensitivity)	TLVDW		• LVDET-0.5V • See Fig. 10.		0.2			ms

Note8-1: The LVD reset level can be selected out of 7 levels only when the LVD reset function is enabled.

Note8-2: LVD reset voltage specification values do not include hysteresis voltage.

Note8-3: LVD reset voltage may exceed its specification values when port output state changes and/or when a large current flows through port.

Note8-4: LVD is in an unknown state before transistors start operation.

$\textbf{Consumption Current Characteristics} \ \ at \ Ta = -40^{\circ}C \ \ to \ +85^{\circ}C, \ V_{SS}\underline{1} = V_{SS}2 = V_{SS}3 = 0V$

Doromotor	Cymphal	Pin/	Conditions			Specific	ation	
Parameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Normal mode consumption current	IDDOP(1)	V _{DD} 1 =V _{DD} 2 =V _{DD} 3	FmCF=12MHz ceramic oscillation mode System clock set to 12MHz side Internal Low speed and Medium speed RC	2.7 to 5.5		6.6	11.3	
(Note 9-1) (Note 9-2)			oscillation stopped. • Frequency variable RC oscillation stopped. • 1/1 frequency division ratio	2.7 to 3.6		4.0	7.3	
	IDDOP(2)		CF1=24MHz external clock System clock set to CF1 side Internal Low speed and Medium speed RC	3.0 to 5.5		8.0	12.7	
		_	oscillation stopped. • Frequency variable RC oscillation stopped. • 1/2 frequency division ratio	3.0 to 3.6		4.6	7.6	
	IDDOP(3)		FmCF=10MHz ceramic oscillation mode System clock set to 10MHz side Internal Low speed and Medium speed RC oscillation stopped.	2.2 to 5.5		5.9	10.5	
			Frequency variable RC oscillation stopped. 1/1 frequency division ratio	2.2 to 3.6		3.6	6.7	
	IDDOP(4)		FmCF=4MHz ceramic oscillation mode System clock set to 4MHz side Internal Low speed and Medium speed RC	1.8 to 5.5		2.6	6.1	
			oscillation stopped. • Frequency variable RC oscillation stopped. • 1/1 frequency division ratio	1.8 to 3.6		1.9	3.9	mA
	IDDOP(5)		CF oscillation low amplifier size selected. (CFLAMP=1) FmCF=4MHz ceramic oscillation mode System clock set to 4MHz side	2.2 to 5.5		0.9	2.2	
			Internal Low speed and Medium speed RC oscillation stopped. Frequency variable RC oscillation stopped. 1/4 frequency division ratio	2.2 to 3.6		0.5	1.1	
	IDDOP(6)	_	FsX'tal=32.768kHz Crystal oscillation mode Internal Low speed RC oscillation stopped. System clock set to internal Medium speed RC	1.8 to 5.5		0.5	1.5	
			oscillation. • Frequency variable RC oscillation stopped. • 1/2 frequency division ratio	1.8 to 3.6		0.3	0.8	
	IDDOP(7)	-	FsX'tal=32.768kHz crystal oscillation mode Internal Low speed and Medium speed RC oscillation stopped.	2.7 to 5.5		5.6	10.8	
			System clock set to 8MHz with Frequency variable RC oscillation 1/1 frequency division ratio	2.7 to 3.6		3.8	6.6	
	IDDOP(8)		External FsX'tal and FmCF oscillation stopped. System clock set to internal Low speed RC oscillation.	1.8 to 5.5		70	173	
			Internal Medium speed RC oscillation stopped. Frequency variable RC oscillation stopped. 1/1 frequency division ratio	1.8 to 3.6		47	106	
	IDDOP(9)		External FsX'tal and FmCF oscillation stopped. System clock set to internal Low speed RC	5.0		70	145	μА
		•1	oscillation. Internal Medium speed RC oscillation stopped. Frequency variable RC oscillation stopped.	3.3		47	86	
			1/1 frequency division ratio Ta=-10 to +50°C	2.5		35	65	

Note 9-1: The consumption current value includes none of the currents that flow into the output Tr and internal pull-up resistors.

Note9-2: The consumption current values do not include operational current of LVD function if not specified

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Parameter	Symbol	Pin/	Conditions			Specific	ation	
		Remarks		V _{DD} [V]	min	typ	max	unit
Normal mode consumption current	, , , , ,					27	120	
(Note 9-1) (Note 9-2)			oscillation stopped. • Frequency variable RC oscillation stopped. • 1/2 frequency division ratio	1.8 to 3.6		13	59	
	IDDOP(11)		FsX'tal=32.768kHz crystal oscillation mode System clock set to 32.768kHz side	5.0		27	84	μА
			Internal Low speed and Medium speed RC oscillation stopped.	3.3		13	33	
			Frequency variable RC oscillation stopped. 1/2 frequency division ratio Ta=-10 to +50°C	2.5		8.1	22	
HALT mode consumption current (Note 9-1)	IDDHALT(1)	V _{DD} 1	HALT mode FmCF=12MHz ceramic oscillation mode System clock set to 12MHz side Internal Low speed and Medium speed RC	2.7 to 5.5		2.6	4.7	
(Note 9-2)			oscillation stopped. • Frequency variable RC oscillation stopped. • 1/1 frequency division ratio	2.7 to 3.6		1.4	2.5	
	IDDHALT(2)		HALT mode CF1=24MHz external clock System clock set to CF1 side Internal Low speed and Medium speed RC	3.0 to 5.5		4.0	6.9	
			oscillation stopped. • Frequency variable RC oscillation stopped. • 1/2 frequency division ratio	3.0 to 3.6		2.0	3.4	
	IDDHALT(3)		HALT mode FmCF=10MHz ceramic oscillation mode System clock set to 10MHz side	2.2 to 5.5		2.2	4.4	
			Internal Low speed and Medium speed RC oscillation stopped. Frequency variable RC oscillation stopped. 1/1 frequency division ratio	2.2 to 3.6		1.2	2.3	
	IDDHALT(4)		HALT mode FmCF=4MHz ceramic oscillation mode System clock set to 4MHz side	1.8 to 5.5		1.2	3.0	mA
			Internal Low speed and Medium speed RC oscillation stopped. Frequency variable RC oscillation stopped. 1/1 frequency division ratio	1.8 to 3.6		0.6	1.4	
	IDDHALT(5)		HALT mode CF oscillation low amplifier size selected. (CFLAMP=1) FmCF=4MHz ceramic oscillation mode	2.2 to 5.5		0.6	1.5	
			System clock set to 4 MHz side Internal Low speed and Medium speed RC oscillation stopped. Frequency variable RC oscillation stopped. 1/4 frequency division ratio	2.2 to 3.6		0.3	0.7	
	IDDHALT(6)	-	HALT mode FsX'tal=32.768 kHz crystal oscillation mode Internal Low speed RC oscillation stopped. System clock set to internal Medium speed RC	1.8 to 5.5		0.3	0.9	
			oscillation • Frequency variable RC oscillation stopped. • 1/2 frequency division ratio	1.8 to 3.6		0.2	0.5	

Note 9-1: The consumption current value includes none of the currents that flow into the output Tr and internal pull-up resistors.

Note9-2: The consumption current values do not include operational current of LVD function if not specified

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Parameter	Symbol	Pin/	Conditions	\/ E.C		Specific		unit
UAI T	IDDUALT/7\	remarks	a HALT mode	V _{DD} [V]	min.	typ.	max.	unit
HALT mode consumption current	IDDHALT(7)	V _{DD} 1	HALT mode FsX'tal=32.768kHz crystal oscillation mode Internal Low speed and Medium speed RC	2.7 to 5.5		2.5	5.0	
(Note 9-1) (Note 9-2)			oscillation stopped. • System clock set to 8MHz with Frequency variable RC oscillation • 1/1 frequency division ratio	2.7 to 3.6		1.4	2.6	
	IDDHALT(8)		HALT mode External FsX'tal and FmCF oscillation stopped. System clock set to internal Low speed RC oscillation.	1.8 to 5.5		26	91	
			Internal Medium speed RC oscillation stopped. Frequency variable RC oscillation stopped. 1/1 frequency division ratio	1.8 to 3.6		15	48	
	IDDHALT(9)		HALT mode External FsX'tal and FmCF oscillation stopped. System clock set to internal Low speed RC	5.0		26	52	
			oscillation. Internal Medium speed RC oscillation stopped.	3.3		15	26	μА
			Frequency variable RC oscillation stopped. 1/1 frequency division ratio Ta=-10 to +50°C	2.5		10	18	
	IDDHALT(10)		HALT mode FsX'tal=32.768 kHz crystal oscillation mode System clock set to 32.768kHz side	1.8 to 5.5		16	96	
			Internal Low speed and Medium speed RC oscillation stopped. Frequency variable RC oscillation stopped. 1/2 frequency division ratio	1.8 to 3.6		6.2	43	
	IDDHALT(11)		HALT mode FsX'tal=32.768kHz crystal oscillation mode	5.0		16	56	
			System clock set to 32.768kHz side Internal Low speed and Medium speed RC oscillation stopped.	3.3		6.2	18	
			Frequency variable RC oscillation stopped. 1/2 frequency division ratio Ta=-10 to +50°C	2.5		3.4	11	
HOLD mode	IDDHOLD(1)	V _{DD} 1	HOLD mode	1.8 to 5.5		0.04	30	
consumption			CF1=V _{DD} or open (External clock mode)	1.8 to 3.6		0.02	14	
(Note 9-1)	IDDHOLD(2)	=	HOLD mode	5.0		0.04	2.8	
(Note 9-2)			• CF1=V _{DD} or open	3.3		0.02	1.2	
			(External clock mode) • Ta=-10 to +50°C	2.5		0.015	0.9	
	IDDHOLD(3)	-	HOLD mode	1.8 to 5.5		2.9	35	
			CF1=V _{DD} or open (External clock mode) LVD option selected	1.8 to 3.6		2.2	18	_
	IDDHOLD(4)	1	HOLD mode	5.0		2.9	7.2	μA
			CF1=V _{DD} or open (External clock mode)	3.3		2.2	4.1	
			Ta=-10 to +50°C LVD option selected	2.5		1.9	3.4	
Timer HOLD	IDDHOLD(5)	V _{DD} 1	Timer HOLD mode	1.8 to 5.5		14	89	
mode			FsX'tal=32.768kHz crystal oscillation mode	1.8 to 3.6		4.8	38	İ
consumption	IDDHOLD(6)	1	Timer HOLD mode	5.0		14	40	
current (Note 9-1)			• FsX'tal=32.768kHz crystal oscillation mode	3.3		4.8	15	I
(Note 9-2)			• Ta=-10 to +50°C	2.5		2.4	7.6	

Note 9-1: The consumption current value includes none of the currents that flow into the output Tr and internal pull-up resistors.

Note9-2: The consumption current values do not include operational current of LVD function if not specified

F-ROM Programming Characteristics at $Ta = -10^{\circ}C$ to $+55^{\circ}C$, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

D	Symbol Pin/Remarks		O and distance		Specification				
Parameter			Conditions	V _{DD} [V]	min	typ	max	unit	
Onboard programming current	IDDFW(1)	V _{DD} 1	Only current of the Flash block.	2.2 to 5.5		5	10	mA	
Programming	tFW(1)		Erasing time	0.04- 5.5		20	30	ms	
time	tFW(2)		Programming time	2.2 to 5.5		40	60	μs	

UART (Full Duplex) Operating Conditions at Ta = -40 °C to +85 °C, VSS1 = VSS2 = VSS3 = 0V

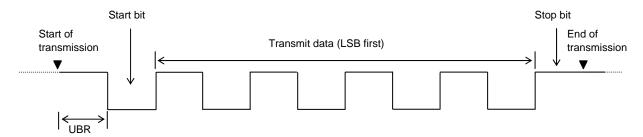
Danamatan	O. made al	Dia /Damania	O and distance		Specification				
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit	
Transfer rate	UBR	UTX(P20), URX(P21)		1.8 to 5.5	16/3		8192/3	tCYC	

Data length: 7, 8, and 9 bits (LSB first)

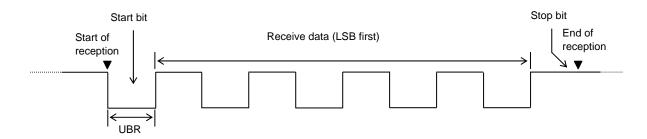
Stop bits: 1 bit (2-bit in continuous data transmission)

Parity bits: None

Example of Continuous 8-bit Data Transmission Mode Processing (first transmit data=55H)



Example of Continuous 8-bit Data Reception Mode Processing (first receive data=55H)



Characteristics of a Sample Main System Clock Oscillation Circuit

Given below are the characteristics of a sample main system clock oscillation circuit that are measured using a Our designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

Table 1 Characteristics of a Sample Main System Clock Oscillator Circuit with a Ceramic Oscillator

• CF oscillation normal amplifier size selected (CFLAMP=0)

Nominal Frequency	Vendor		Circuit Constant				Operating	Oscillation Stabilization Time						
	Name	Oscillator Name	C1 [pF]	C2 [pF]	Rf1 [Ω]	Rd1 [Ω]	Voltage Range [V]	typ [ms]	max [ms]	Remarks				
12MHz		CSTCE12M0G52-R0	(10)	(10)	Open	680	2.7 to 5.5	0.1	0.5					
		CSTCE10M0G52-R0	(10)	(10)	Open	680	2.2 to 5.5	0.1	0.5					
10MHz		CSTLS10M0G53-B0	(15)	(15)	Open	680	2.2 to 5.5	0.1	0.5	Internal C1,C2				
OMILI-		CSTCE8M00G52-R0	(10)	(10)	Open	1.0k	2.2 to 5.5	0.1	0.5					
8MHz	MURATA	CSTLS8M00G53-B0	(15)	(15)	Open	1.0k	2.2 to 5.5	0.1	0.5					
CMI I-						CSTCR6M00G53-R0	(15)	(15)	Open	1.5k	2.2 to 5.5	0.1	0.5	01,02
6MHz		CSTLS6M00G53-B0	(15)	(15)	Open	1.5k	2.2 to 5.5	0.1	0.5					
4MHz		CSTCR4M00G53-R0	(15)	(15)	Open	1.5k	1.8 to 5.5	0.2	0.6					
4IVIHZ		CSTLS4M00G53-B0	(15)	(15)	Open	1.5k	1.8 to 5.5	0.2	0.6	ı				

• CF oscillation low amplifier size selected (CFLAMP=1)

Nominal Frequency	Vendor	O. That and have		Circuit (Constant		Operating		lation tion Time	
	Name	Oscillator Name	C1 [pF]	C2 [pF]	Rf1 [Ω]	Rd1 [Ω]	Voltage Range [V]	typ [ms]	max [ms]	Remarks
48.41.1	MURATA	CSTCR4M00G53-R0	(15)	(15)	Open	1.0k	1.9 to 5.5	0.2	0.6	Internal
4MHz		CSTLS4M00G53-B0		(15)	Open	1.0k	1.9 to 5.5	0.2	0.6	C1,C2

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized after V_{DD} goes above the operating voltage lower limit (see Figure 4).

Characteristics of a Sample Subsystem Clock Oscillator Circuit

Given below are the characteristics of a sample subsystem clock oscillation circuit that are measured using a Our designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

Table 2 Characteristics of a Sample Subsystem Clock Oscillator Circuit with a Crystal Oscillator

Nominal		0 111 1 11	Circuit Constant				Operating Voltage	Oscillation Stabilization Time		Damada	
	Frequency	Vendor Name	Oscillator Name	C3 [pF]	C4 [pF]	Rf2 [Ω]	Rd2 [Ω]	Range [V]	typ	max [s]	Remarks
ŀ				[bi]	[bi]	[52]	[22]	[1]	[s]	[5]	Applicable
	32.768kHz	EPSON TOYOCOM	MC-306	18	18	Open	330k	1.8 to.5.5	1.4	4.0	CL value= 7.0pF

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized after the instruction for starting the subclock oscillation circuit is executed and to the time interval that is required for the oscillation to get stabilized after the HOLD mode is reset (see Figure 4).

Note: The components that are involved in oscillation should be placed as close to the IC and to one another as possible because they are vulnerable to the influences of the circuit pattern.

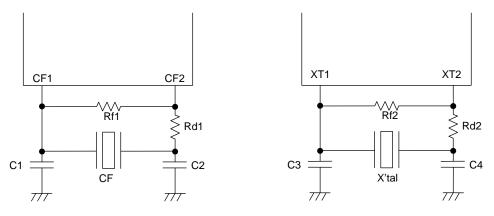
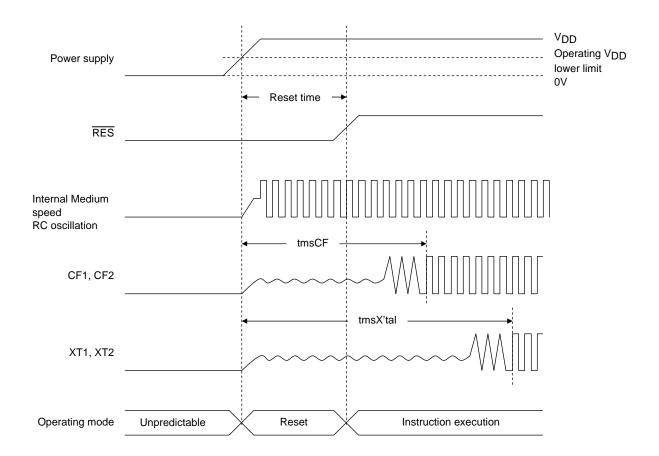


Figure 1 CF Oscillator Circuit

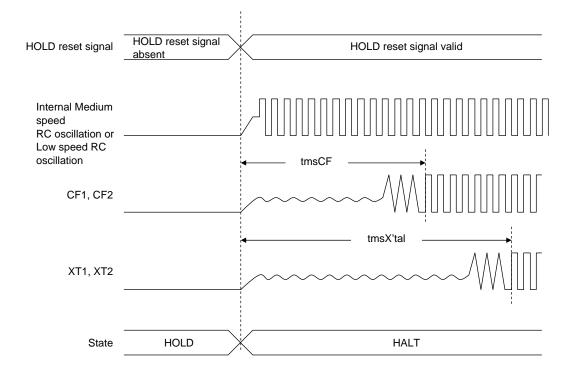
Figure 2 XT Oscillator Circuit



Figure 3 AC Timing Measurement Point



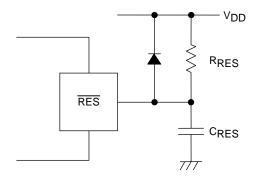
Reset Time and Oscillation Stabilization Time



HOLD Reset Signal and Oscillation Stabilization Time

Note: External oscillation circuit is selected.

Figure 4 Oscillation Stabilization Times



Note:

External circuits for reset may vary depending on the usage of POR and LVD. Please refer to the user's manual for more information.

Figure 5 Reset Circuit

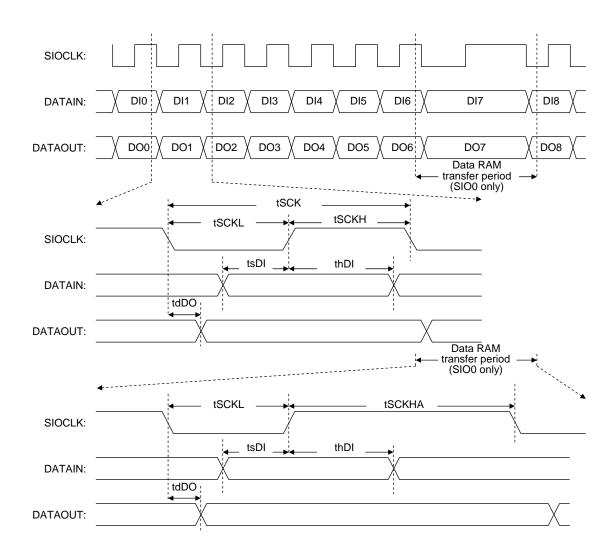


Figure 6 Serial I/O Waveforms

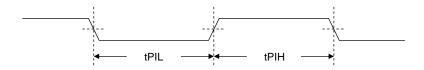


Figure 7 Pulse Input Timing Signal Waveform

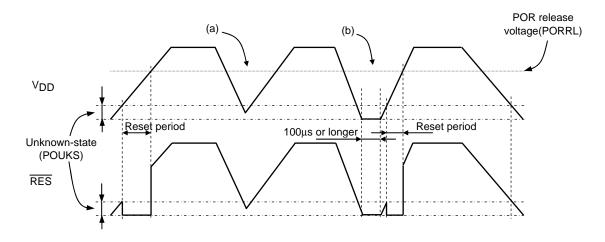


Figure 8 Waveform observed when only POR is used (LVD not used) (RESET pin: Pull-up resistor RRES only)

- The POR function generates a reset only when power is turned on starting at the VSS level.
- No stable reset will be generated if power is turned on again when the power level does not go down to the VSS level as shown in (a). If such a case is anticipated, use the LVD function together with the POR function or implement an external reset circuit.
- A reset is generated only when the power level goes down to the VSS level as shown in (b) and power is turned on again after this condition continues for 100µs or longer.

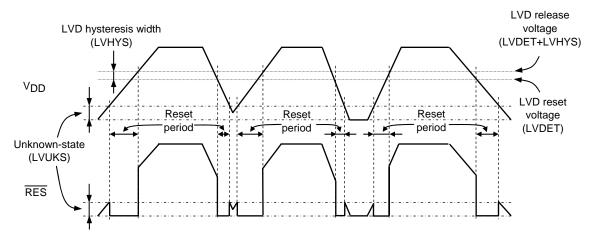


Figure 9 Waveform observed when both POR and LVD functions are used (RESET pin: Pull-up resistor RRES only)

- Resets are generated both when power is turned on and when the power level lowers.
- A hysteresis width (LVHYS) is provided to prevent the repetitions of reset release and entry cycles near the detection level.

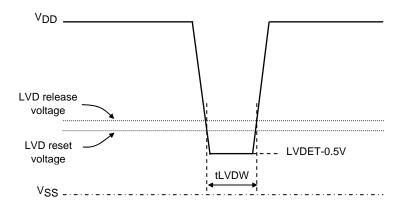


Figure 10 Low voltage detection minimum width (Example of momentary power loss/Voltage variation waveform)

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